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(71) Applicant: **INTERNATIONAL BUSINESS MACHINES CORPORATION** [US/US]; New Orchard Road, Armonk, New York, 10504 (US).

(71) Applicant (for MG only): **IBM UNITED KINGDOM LIMITED** [GB/GB]; PO Box 41, North Harbour, Portsmouth Hampshire PO6 3AU (GB).

(72) Inventors: **LEWANDOWSKI, Eric, Peter**; IBM CORPORATION, PO BOX 218, 1101 KITCHAWAN ROAD, YORKTOWN HEIGHTS, New York 10598 (US). **WEBB, Bucknell**; IBM CORPORATION, PO BOX 218, 1101 KITCHAWAN ROAD, YORKTOWN HEIGHTS, New

York 10598 (US). **HERTZBERG, Jared, Barney**; IBM CORPORATION, PO BOX 218, 1101 KITCHAWAN ROAD, YORKTOWN HEIGHTS, New York 10598 (US). **SANDBERG, Martin**; IBM CORPORATION, PO BOX 218, 1101 KITCHAWAN ROAD, YORKTOWN HEIGHTS, New York 10598 (US). **JINKA, Oblesh**; IBM CORPORATION, PO BOX 218, 1101 KITCHAWAN ROAD, YORKTOWN HEIGHTS, New York 10598 (US).

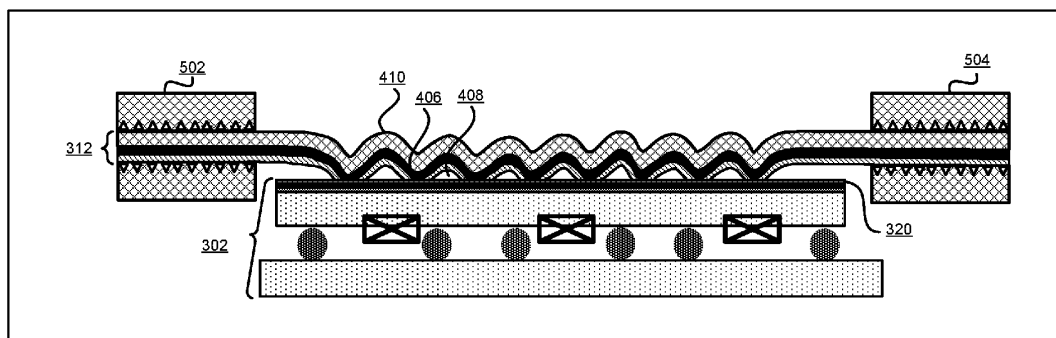
(74) Agent: **WILLIAMS, Julian**; IBM United Kingdom Limited, Intellectual Property Law, Hursley Park, Hursley, Winchester Hampshire SO21 2JN (GB).

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FIGURE 5



(57) Abstract: A thermalization structure is formed using a foil and a low temperature device (LTD). The foil includes a first layer of a first material. The LTD includes a surface from which heat is transferred away from the LTD. A coupling is formed between the foil and the surface of the LTD, where the coupling includes a bond formed between the foil and the surface such that forming the bond forms a set of ridges in the foil, a ridge in the set of ridges operating to dissipate the heat.

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